

# SOT636-1

plastic heatsink ball grid array package; 388 balls; body 35 x 35 x 1.75 mm; heatsink

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	HBGA388
<b>Package type industry code</b>	HBGA388
<b>Package style descriptive code</b>	HBGA (thermal enhanced ball grid array)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>IEC package outline code</b>	144E
<b>JEDEC package outline code</b>	MS-034
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	11-12-2001

Table 1. Package summary

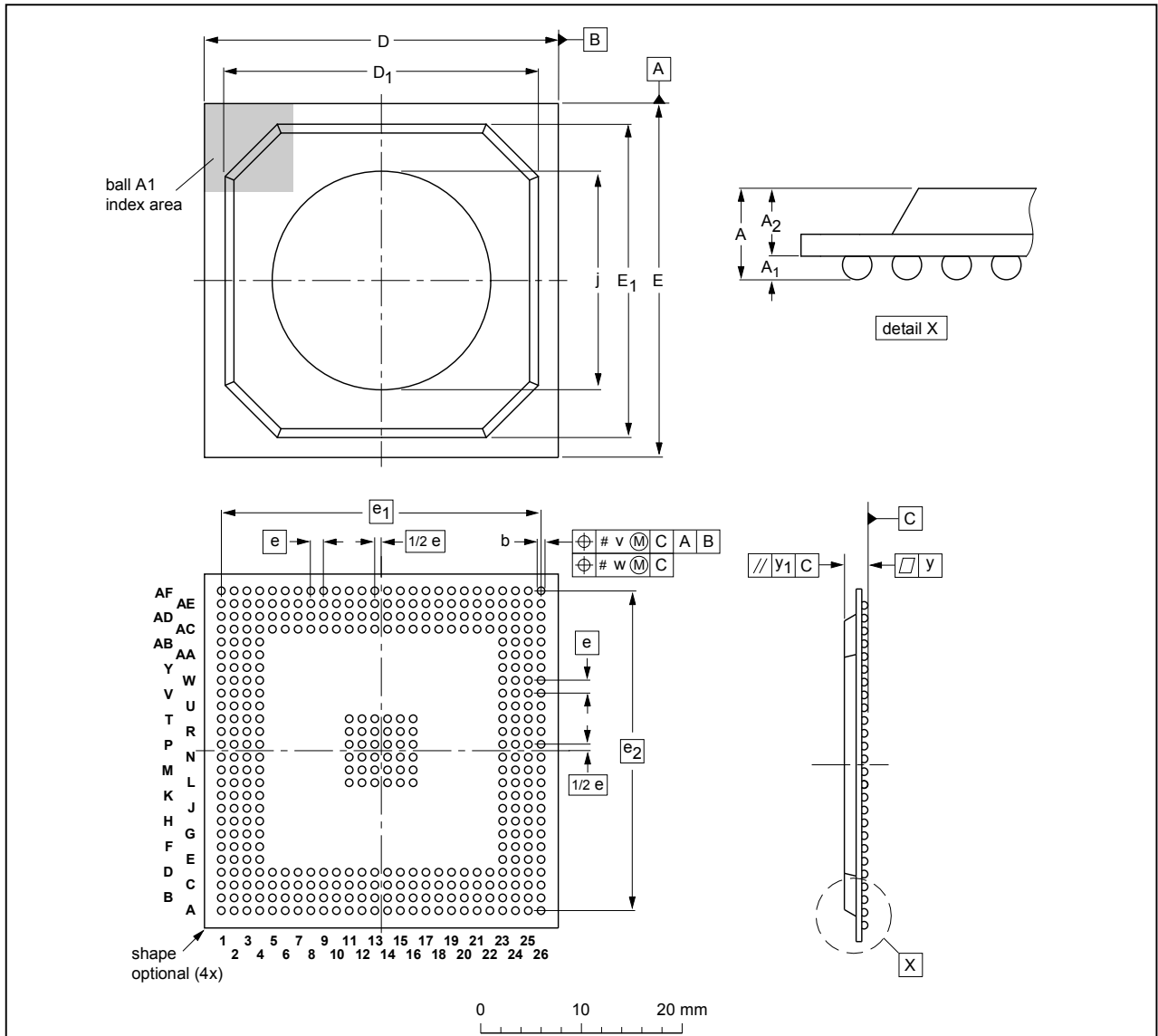
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	34.8	-	35	35.2	mm
E	package width	34.8	-	35	35.2	mm
A	seated height	[tbd]	-	2.55	2.55	mm
A <sub>2</sub>	package height	1.6	-	1.75	1.85	mm
n <sub>2</sub>	actual quantity of termination	-	-	388	-	



## 2. Package outline

HBGA388: plastic thermal enhanced ball grid array package; 388 balls;  
body 35 x 35 x 1.75 mm; heatsink

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DIMENSIONS (mm are the original dimensions)

UNIT	A <sub>max.</sub>	A <sub>1</sub>	A <sub>2</sub>	b	D	D <sub>1</sub>	E	E <sub>1</sub>	e	e <sub>1</sub>	e <sub>2</sub>	j	v	w	y	y <sub>1</sub>
mm	2.55	0.7 0.5	1.85 1.60	0.9 0.6	35.2 34.8	30.75 29.75	35.2 34.8	30.75 29.75	1.27	31.75	31.75	26 22	0.3	0.15	0.2	0.35

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT636-1	144E	MS-034	---			01-04-17 01-12-11

Fig. 1. Package outline HBGA388 (SOT636-1)

### 3. Soldering

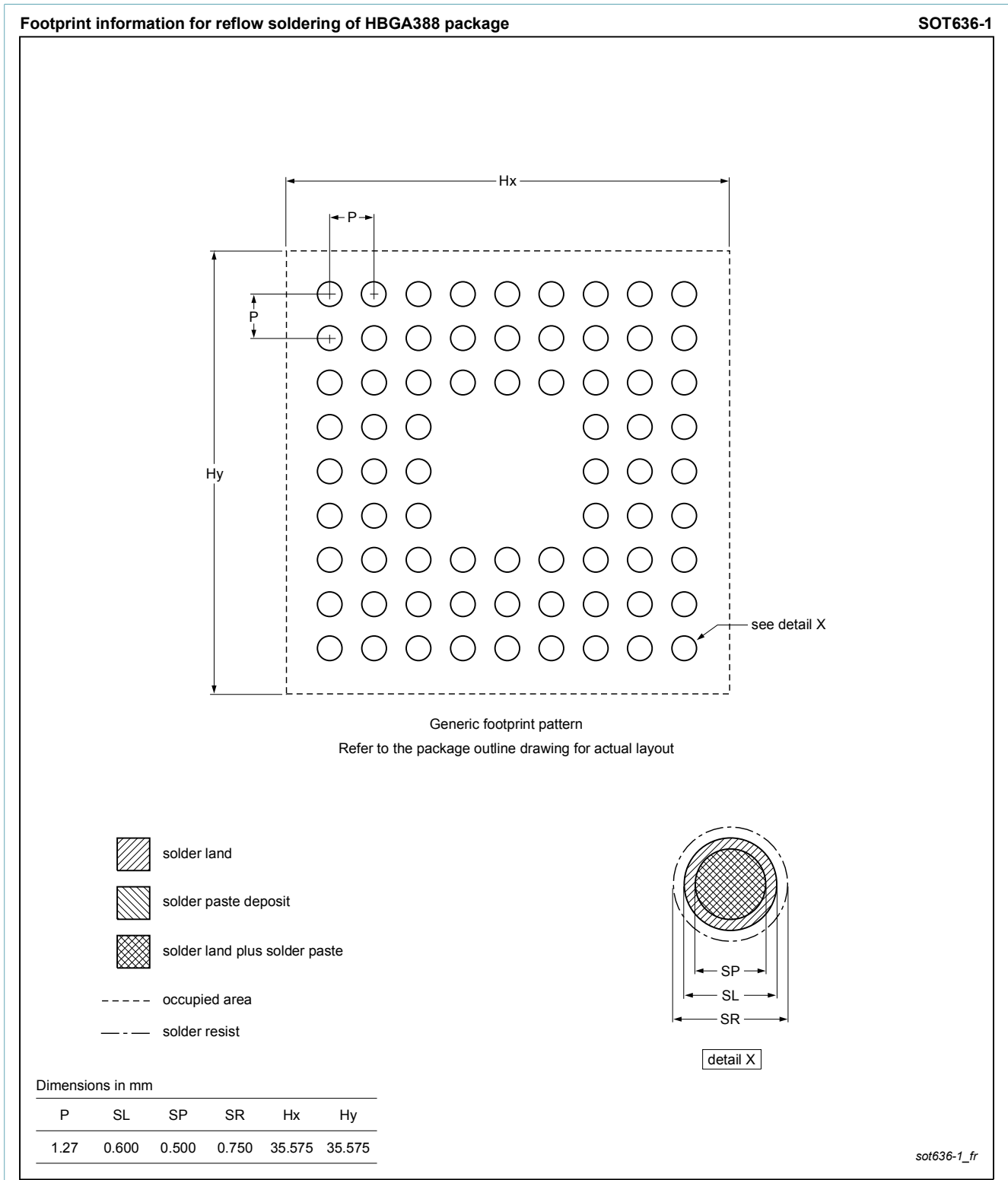


Fig. 2. Reflow soldering footprint for HBGA388 (SOT636-1)

## 4. Legal information

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